



# Material Composition Declaration

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This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

**Adobe Reader version 7.0.5 is required to complete this declaration.**

1752-2 1.1	IPC Web Site for Information on IPC-1752 Standard <a href="http://www.ipc.org/IPC-175x">http://www.ipc.org/IPC-175x</a>	Form Type * Distribute	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Informat
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## Supplier Information

Company Name * STMicroelectronics	Company Unique ID	Unique ID Authority	Response Date * N/A	Response Document ID				
Contact Name *	Title - Contact	Phone - Contact *	Email - Contact *					
Authorized Representative * GIUSEPPE VITALI PALMA	Title - Representative APM MD CHAMPION	Phone - Representative * N/A	Email - Representative * N/A	Supplier Comments or URL for Additional Information				
Requester Item Number	Mfr Item Number	Mfr Item Name	Effective Date	Version	Manufacturing Site	Weight *	UOM	Unit Type
	TSV6311CT	HYW8*V631BRL	2011-01-05	A	ZS1A	6	mg	Each
Alternate Recommendation	PACKAGE: SOT 323 5LDS			Alternate Item Comments	ECOPACK2/ROHS; BSA:CD00275839			

## Manufacturing Process Information

Terminal Plating / Grid Array Material <b>Nickel/Palladium/Gold (Ni/Pd/Au)</b>	Terminal Base Alloy <b>CU Alloy</b>	J-STD-020 MSL Rating <b>1</b>	Peak Process Body Temperature <b>260 C</b>	Max Time at Peak Temperature <b>30 seconds</b>	Number of Reflow Cycles <b>3</b>
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Comments  
**Disclaimer: While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and**

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## RoHS Material Composition Declaration

Declaration Type \*

Simplified

**RoHS Directive 2002/95/EC** **RoHS Definition:** Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium

Supplier certifies that it gathered the information it provides in this form concerning RoHS restrictive substances using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

RoHS Declaration \*

1 - Item(s) does not contain RoHS restricted substances per the definition above

Supplier Acceptance \*

Accepted

**Exemptions:** If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.

## Declaration Signature

**Instructions:** Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.

Supplier Digital Signature

## Homogeneous Material Composition Declaration for Electronic Products

**SubItem Instructions:** The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

**Substance Instructions:** [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

**Line Functions:** +I Inserts a New Item /SubItem +M Inserts a new Material +C Inserts a new Substance Category +S Inserts a new Substance - Deletes the element line

Item/SubItem Name	Homogeneous Material	Weight	Unit of Measure	Level	Substance Category	Substance	CAS	Exempt	Weight	Unit of Measure	Tolerance		PPM
											-	+	
HYW8*V631BRL	Silicon Die	0.3	mg	Supplier	Silicon die	Silicon (Si)	7440-21-3		0.3	mg			1,000,0
	Leadframe	2.8735	mg	Supplier	Alloy	Copper	7440-50-8		2.7685	mg			963,45
						Iron	7439-89-6		0.063	mg			21,924
						Phosphorus	12517-41-8		0.001	mg			348
						Zinc	7440-66-6		0.004	mg			1,393
						Nickel	7440-02-0		0.033	mg			11,484
						Palladium	7440-05-3		0.003	mg			1,044
						Gold	7440-57-5		0.001	mg			348
	Die Attach	0.144	mg	supplier	Glue	Treated Silica	60676-86-0		0.036	mg			250,00
						Glycol Ethers	Proprietary		0.027	mg			187,50
						Metal Oxide	1344-28-1		0.041	mg			284,72
						Epoxy Resin	25068-38-6		0.035	mg			243,05
						Aromatic amine	Proprietary		0.005	mg			34,722
	Bonding wire	0.08	mg	supplier	Bonding wire	Gold (Au)	7440-57-5		0.08	mg			1,000,0
	Encapsulation	2.603	mg	supplier	Molding compound	Epoxy resin	Proprietary		0.104	mg			39,962
						Biphenyl epoxy resin	85954-11-6		0.052	mg			19,981
						Phenol resin	Proprietary		0.092	mg			35,351
						Silica, vitreous	60676-86-0		2.2195	mg			852,83
						Carbon Black	1333-86-4		0.005	mg			1,921
						Zinc hydroxide	20427-58-1		0.026	mg			9,990
						Magnesium hydroxide	1309-42-8		0.104	mg			39,962